

General Purpose NPN Epitaxial Planar Transistor

BTC3906S3

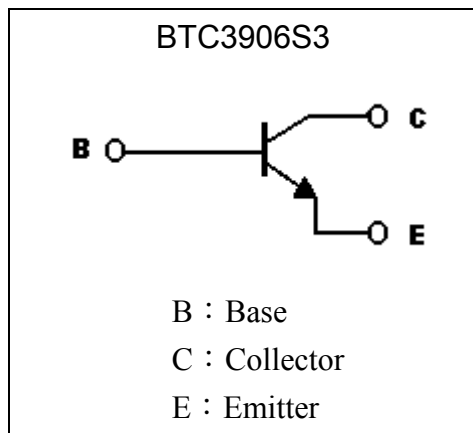
Description

The BTC3906S3 is designed for general purpose applications requiring high breakdown voltage.

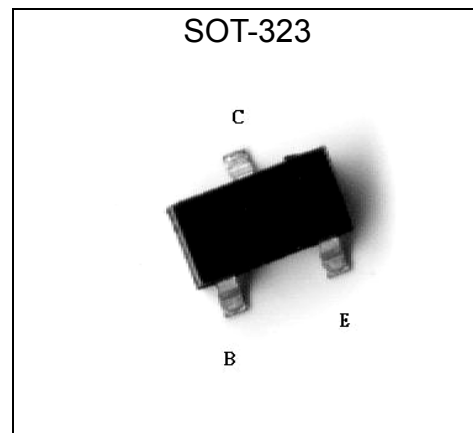
Features

- High collector-emitter breakdown voltage. ($BV_{CEO}=160V @ I_C=1mA$)
- Complement to BTA1514S3
- Pb-free and halogen-free package

Symbol

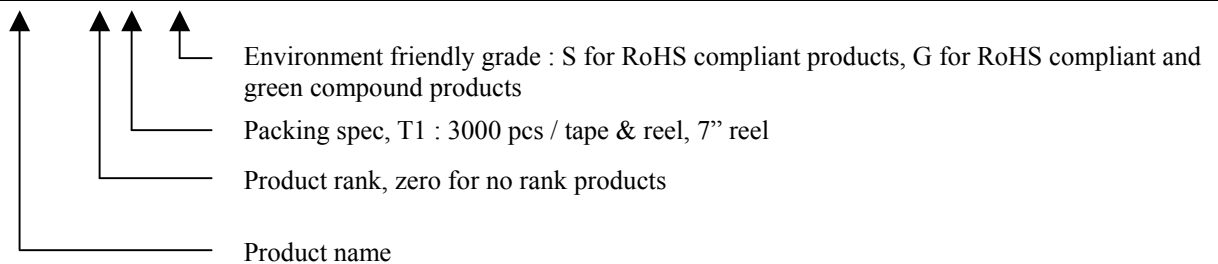


Outline



Ordering Information

Device	Package	Shipping
BTC3906S3-X-T1-G	SOT-323 (Pb-free and halogen-free package)	3000 pcs / Tape & Reel





Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CB0}	180	V
Collector-Emitter Voltage	V _{CEO}	160	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current	I _C	600	mA
Power Dissipation (T _A =25°C)	P _D	200	mW
Thermal Resistance, Junction to Ambient	R _{θJA}	625	°C/W
Operating Junction Temperature Range	T _j	-55~+150	°C
Storage Temperature Range	T _{stg}	-55~+150	°C

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	180	-	-	V	I _C =100μA
BV _{CEO}	160	-	-	V	I _C =1mA
BV _{EBO}	6	-	-	V	I _E =10μA
I _{CB0}	-	-	50	nA	V _{CB} =120V
I _{EBO}	-	-	50	nA	V _{EB} =4V
*V _{CE(sat)1}	-	0.1	0.15	V	I _C =10mA, I _B =1mA
*V _{CE(sat)2}	-	-	0.2	V	I _C =50mA, I _B =5mA
*V _{BE(sat)1}	-	-	1	V	I _C =10mA, I _B =1mA
*V _{BE(sat)2}	-	-	1	V	I _C =50mA, I _B =5mA
*h _{FE1}	100	-	-	-	V _{CE} =5V, I _C =1mA
*h _{FE2}	100	-	-	-	V _{CE} =5V, I _C =10mA
*h _{FE3}	50	-	-	-	V _{CE} =5V, I _C =50mA
*h _{FE4}	120	-	390	-	V _{CE} =6V, I _C =2mA
f _T	100	-	-	MHz	V _{CE} =20V, I _C =10mA, f=100MHz
C _{ob}	-	-	6	pF	V _{CB} =20V, I _E =0A, f=1MHz

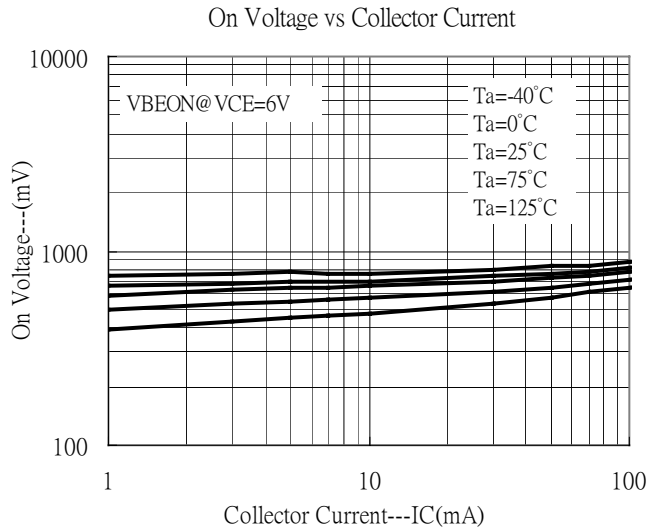
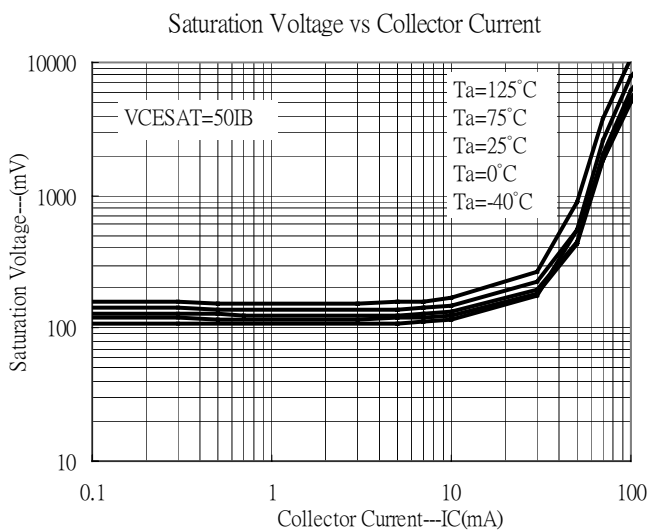
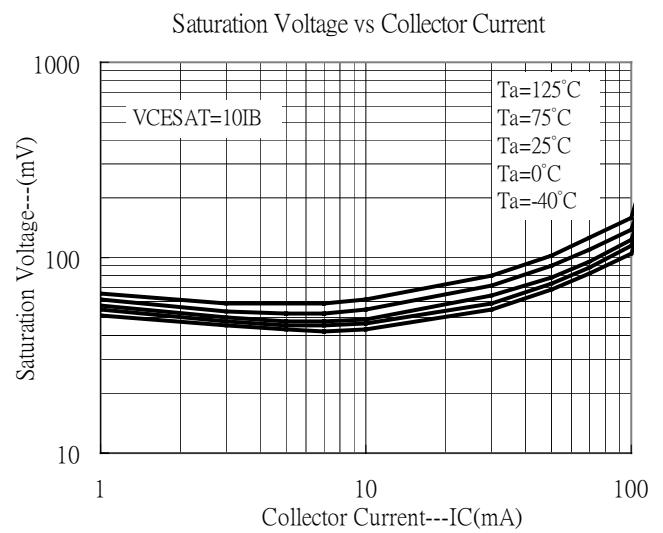
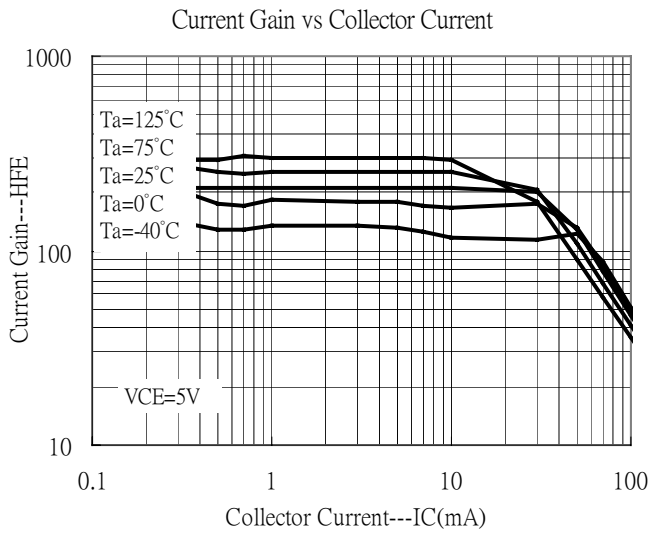
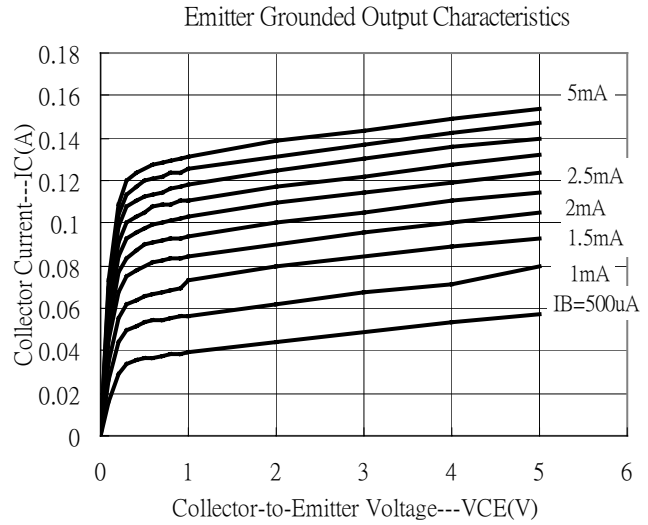
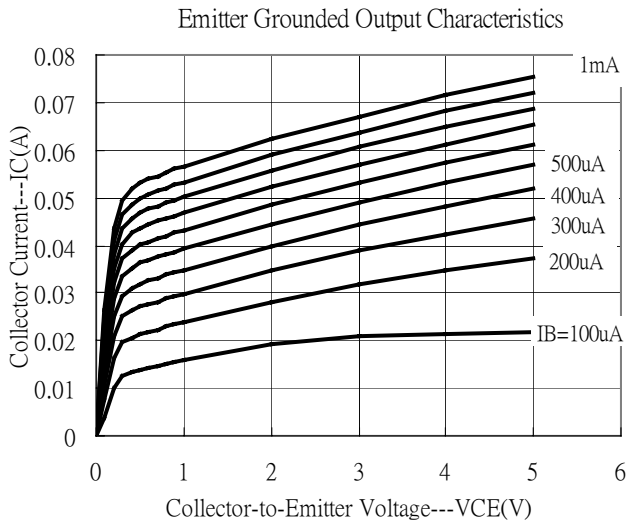
*Pulse Test: Pulse Width ≤380us, Duty Cycles ≤2%

Classification Of h_{FE} 4

Rank	Q	R
Range	120~270	180~390

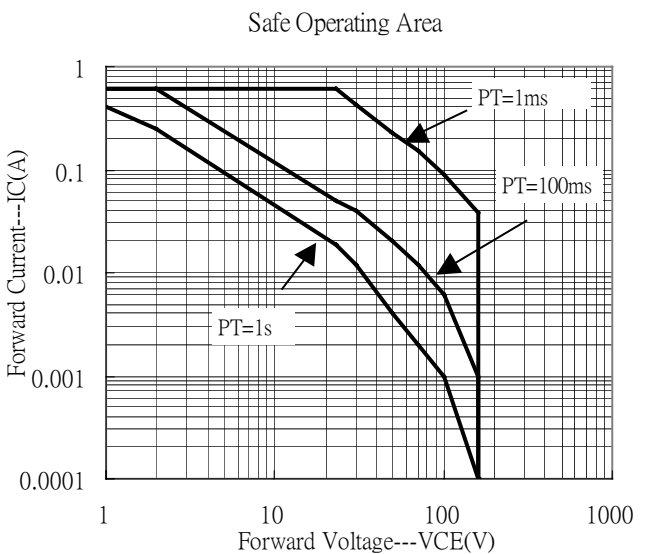
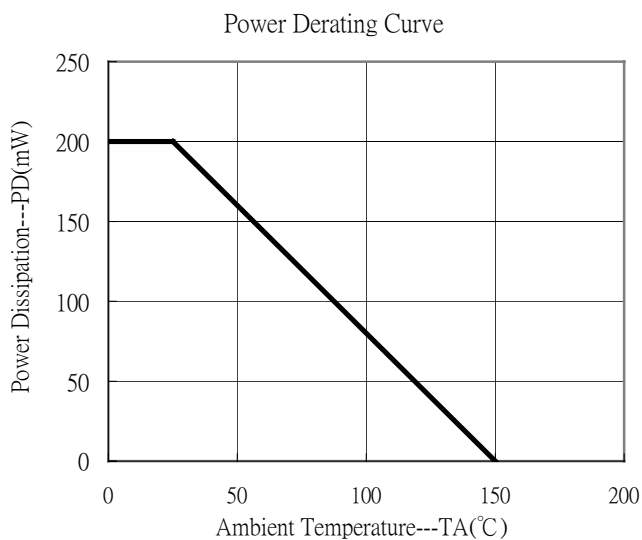
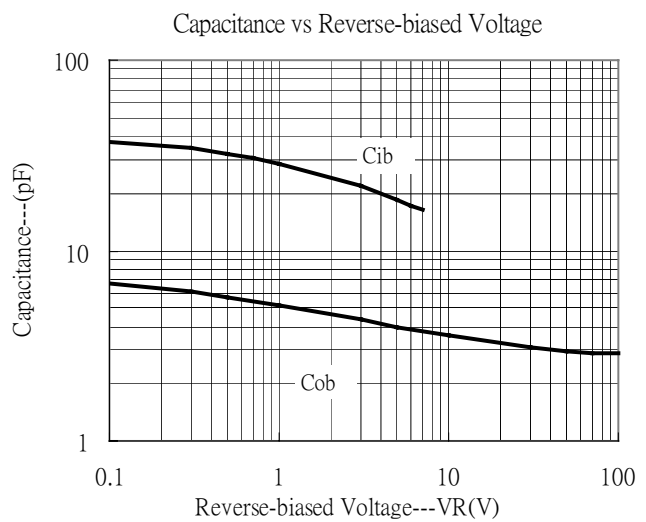
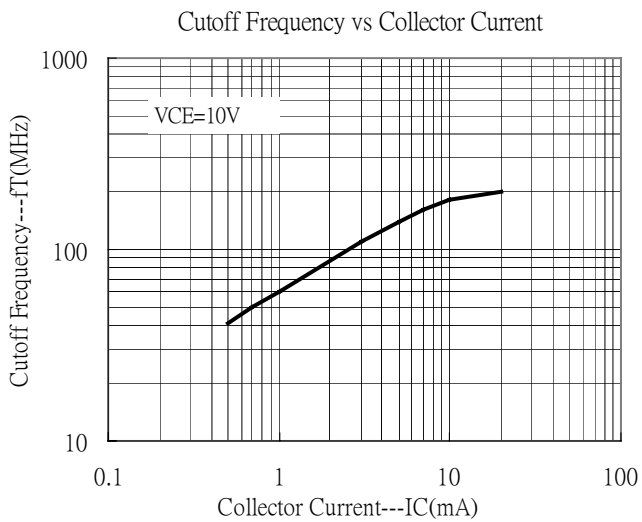
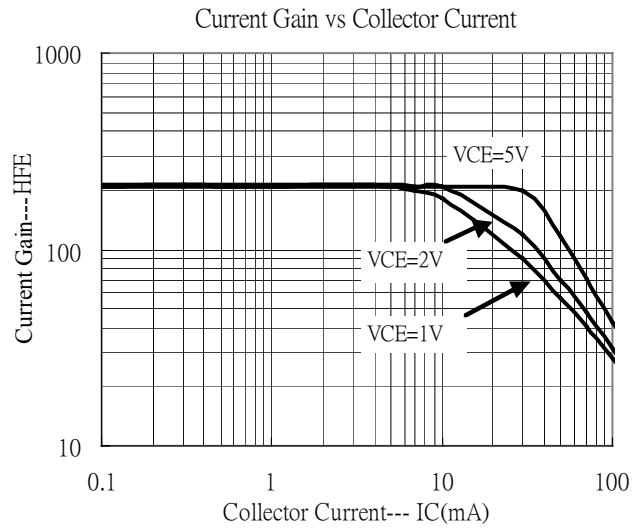
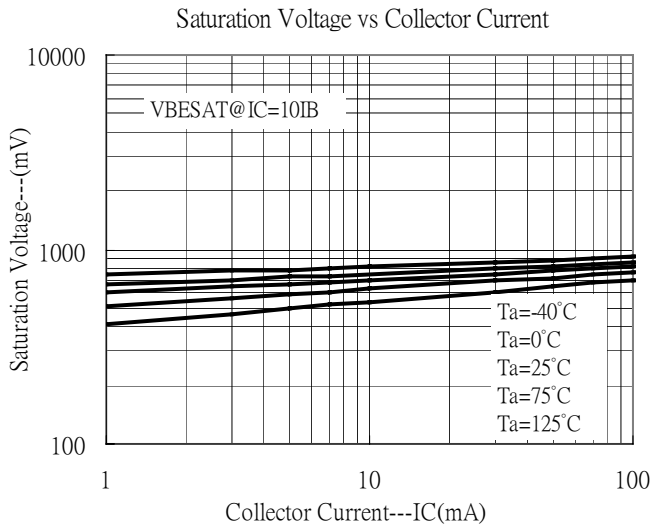


Typical Characteristics

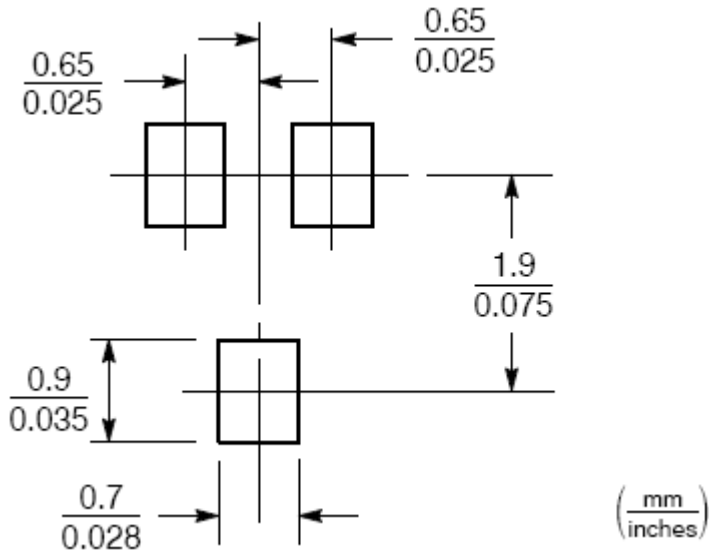




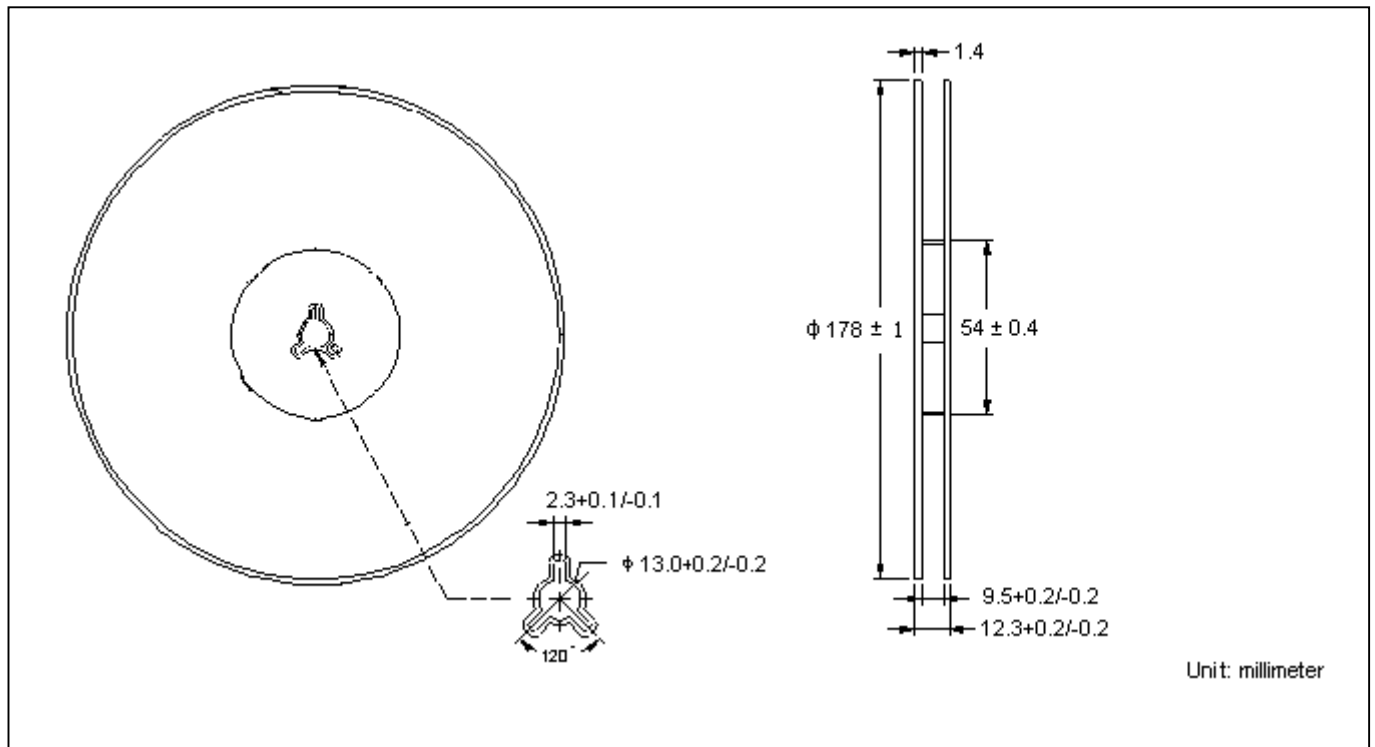
Typical Characteristics(Cont.)



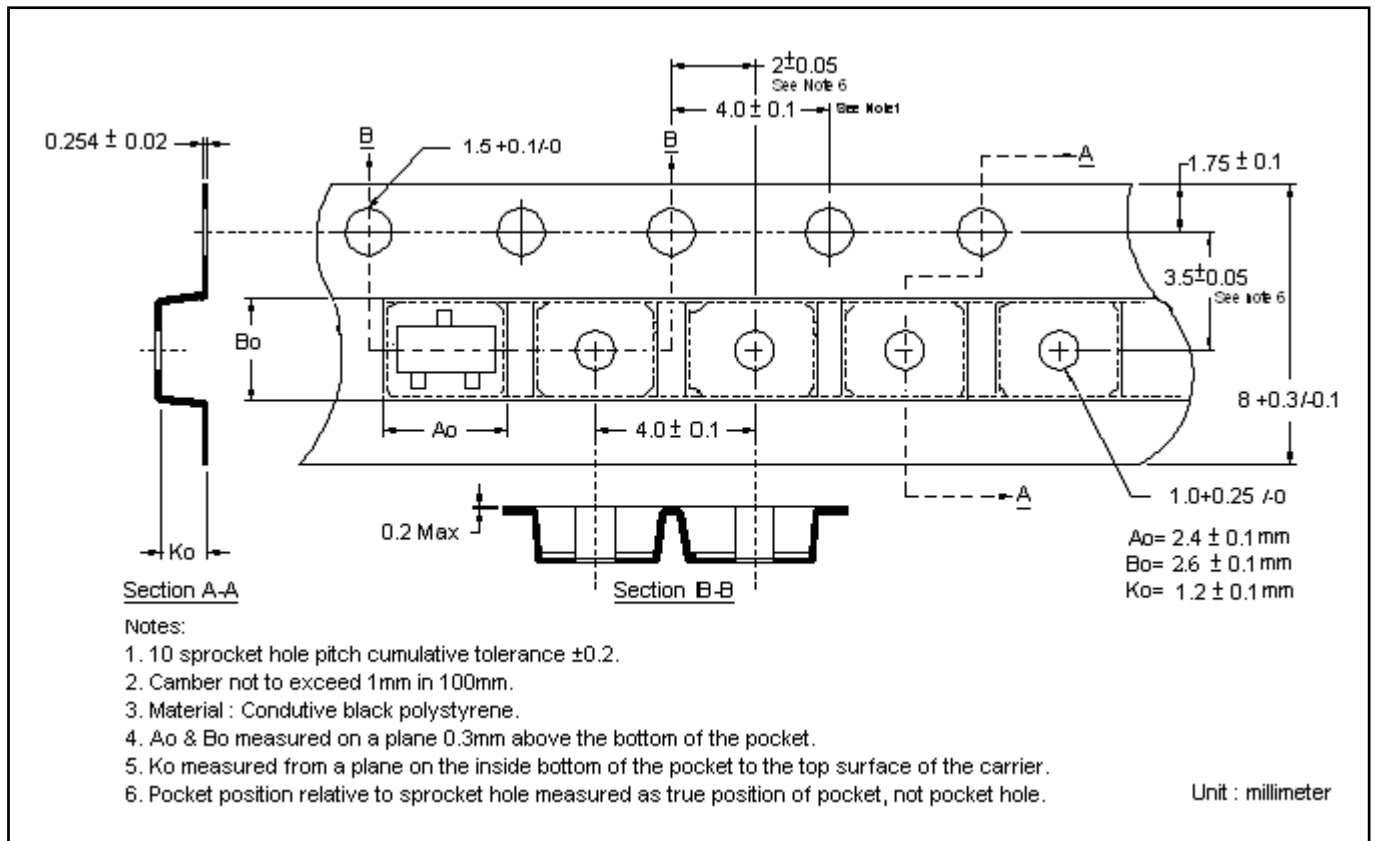
Recommended Soldering Footprint



Reel Dimension



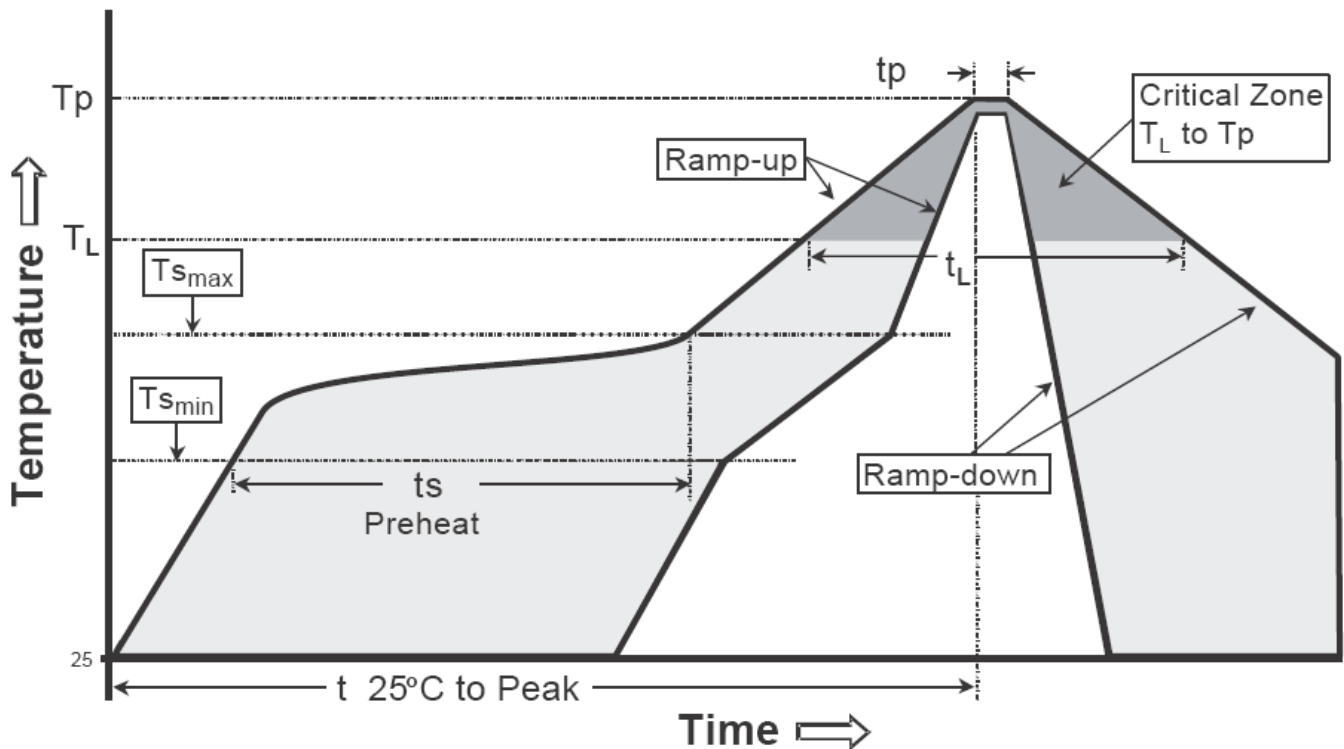
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

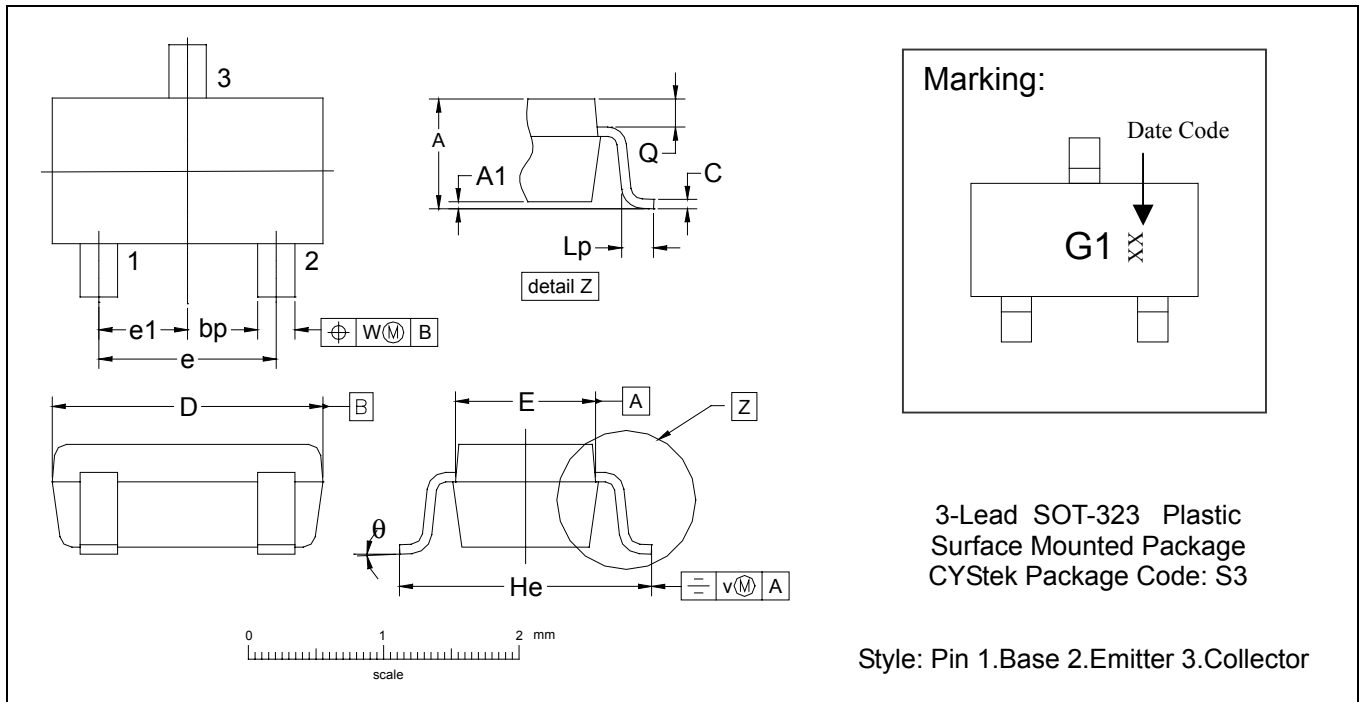
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note :1. All temperatures refer to topside of the package, measured on the package body surface.
 2.For devices mounted on FR-4 PCB of 1.6mm or equivalent grade PCB. If other grade PCB is used, care should be taken to match the coefficients of thermal expansion between components and PCB. If they are not matched well, the solder joints may crack or the bodies of the parts may crack or shatter as the assembly cools.

SOT-323 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0315	0.0433	0.80	1.10	e1	0.0256*		0.65*	
A1	0.0000	0.0039	0.00	0.10	He	0.0846	0.0965	2.15	2.45
bp	0.0078	0.0157	0.20	0.40	Lp	0.0105	0.0181	0.26	0.46
C	0.0031	0.0059	0.08	0.15	Q	0.0051	0.0091	0.13	0.23
D	0.0709	0.0866	1.80	2.20	v	0.0079	-	0.2	-
E	0.0453	0.0531	1.15	1.35	w	0.0079	-	0.2	-
e	0.0472	0.0551	1.20	1.40	theta	0°	8°	0°	8°

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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